

CD/Overlay Measurement System

Fulfill all your needs with limited budget

■ Features

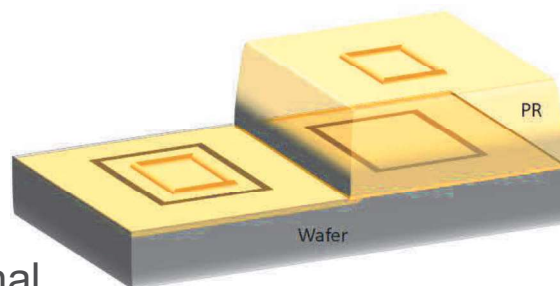
- Auto overlay & CD analysis
- Adapt to extra wide step height layer pattern
- Adapt to multi-layer film or wafer
- Adapt to Si, GaAs, SiC, glass... wafer
- Merge 3D function for step height analysis

■ Specifications

- Robot handler, Pre-aligner, OCR, SECS/GEM
- Film range: **upper than 30um** (100 um option)
- Image Resolution/ FOV: 0.11 um /0.22 mm x 0.12 mm @50X
- Repeatability: better than 20 nm (include TIS error)
- Pattern: **Box In Box, AIM (inside chip layer pattern or customized)**
- Data output: X/Y- shift, X/Y-Mag, X/Y- Rot, Shot Mag/Rot

■ Applications

- Semiconductor AEI/ADI layer shift measurement (5G, RF,CIS, Power device...)
- Follow Stepper & Aligner



Traditional

(two patterns almost in the same level)

New

(two patterns separate far away)

